

ABSTRACT OF THE DISCLOSURE

The present invention provides a semiconductor structure including a substrate, a metal reflective layer, a UV glue layer, and an element. The metal reflective layer is placed on the surface of the substrate, and the UV glue layer is placed on the surface of the metal reflective layer. The element is manufactured by light-transparent material. The UV glue layer adheres the element to the metal reflective layer. By so, in the light-curing process, the curing of the UV glue is accelerated due to the metal reflective layer reflecting an ultraviolet ray.

FIG. 1